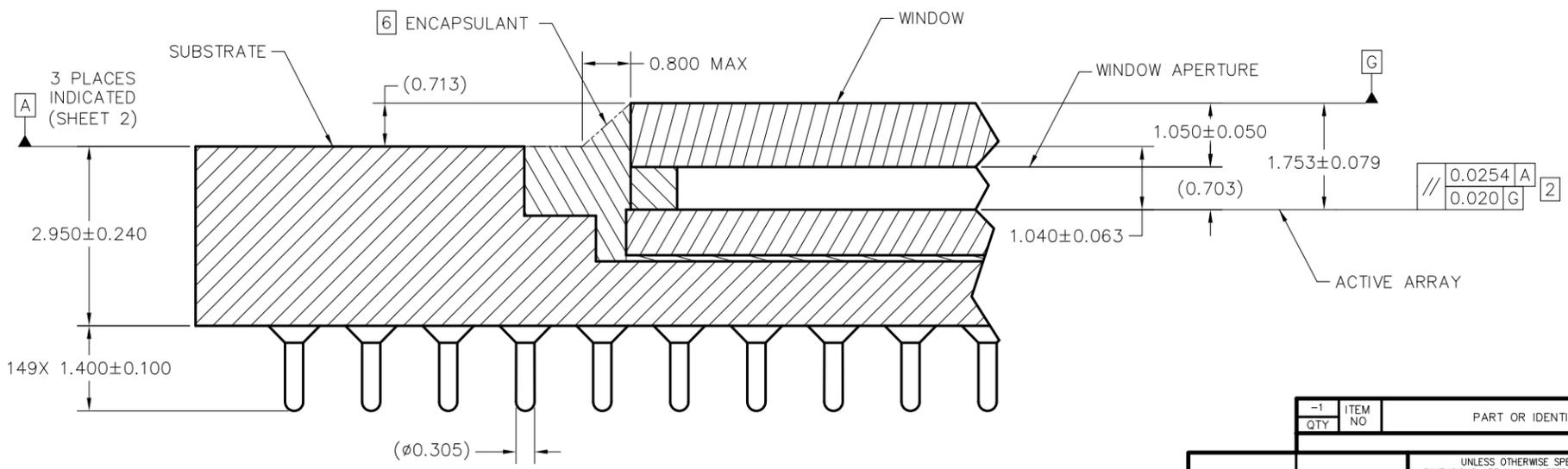
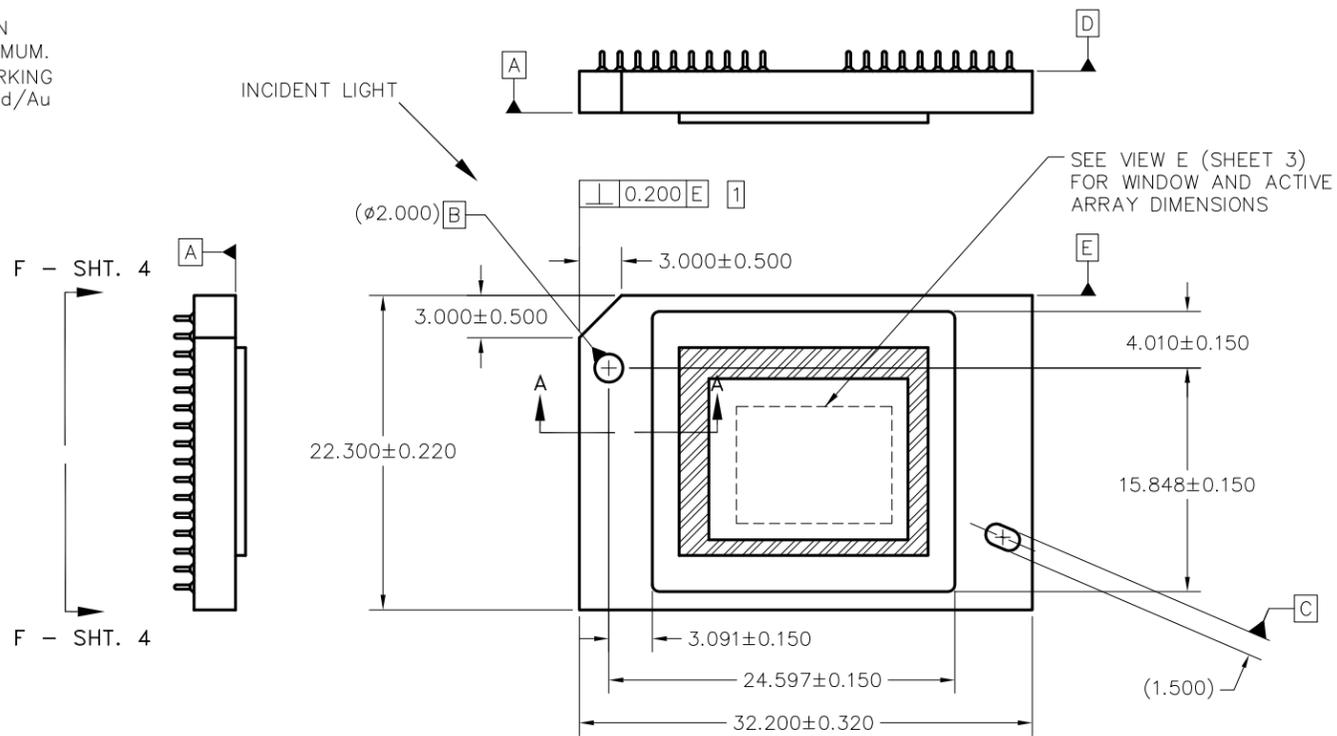


| REVISIONS | | | |
|-----------|---|------------|--------------|
| REV | DESCRIPTION | DATE | APPROVED |
| A | ECO 2121693, INITIAL RELEASE | 01/17/2012 | F. ARMSTRONG |
| B | ECO 2123271, CHG TO LARGE SYMBOLIZATION PAD | 03/16/2012 | F. ARMSTRONG |
| C | ECO 2135103, ADD NOTE 8 TO SHEETS 1 & 4 | 08/02/2013 | F. ARMSTRONG |
| D | ECO 2168422, ADD FYA PACKAGE TO TITLE | 08/17/17 | M. AVERY |

NOTES: UNLESS OTHERWISE SPECIFIED:

- 1 SUBSTRATE EDGE PERPENDICULARITY TOLERANCE APPLIES TO ENTIRE SURFACE
- 2 DIE PARALLELISM TOLERANCE APPLIES TO DMD ACTIVE ARRAY ONLY
- 3 ROTATION ANGLE OF DMD ACTIVE ARRAY IS A REFINEMENT OF THE LOCATION TOLERANCE AND HAS A MAXIMUM ALLOWED VALUE OF 0.8 DEGREES
- 4 SUBSTRATE SYMBOLIZATION PAD, AND PLATING AT BOTTOM OF DATUMS B AND C HOLES TO BE ELECTRICALLY CONNECTED TO VSS PLANE WITHIN THE SUBSTRATE
- 5 BOUNDARY MIRRORS SURROUNDING THE DMD ACTIVE AREA
- 6 MAXIMUM ENCAPSULANT PROFILE SHOWN
- 7 ENCAPSULANT ALLOWED ON THE SURFACE OF THE CERAMIC IN THE AREA SHOWN IN VIEW B (SHEET 2). ENCAPSULANT SHALL NOT EXCEED 0.200 THICKNESS MAXIMUM.
- 8 SUBSTRATES PLATED WITH Ni/Au SHALL HAVE THE THREE-DIGIT NUMERICAL MARKING IN THE AREA ABOVE THE SYMBOLIZATION PAD. SUBSTRATES PLATED WITH Ni/Pd/Au SHALL HAVE THE MARKING IN THE AREA BELOW THE SYMBOLIZATION PAD.

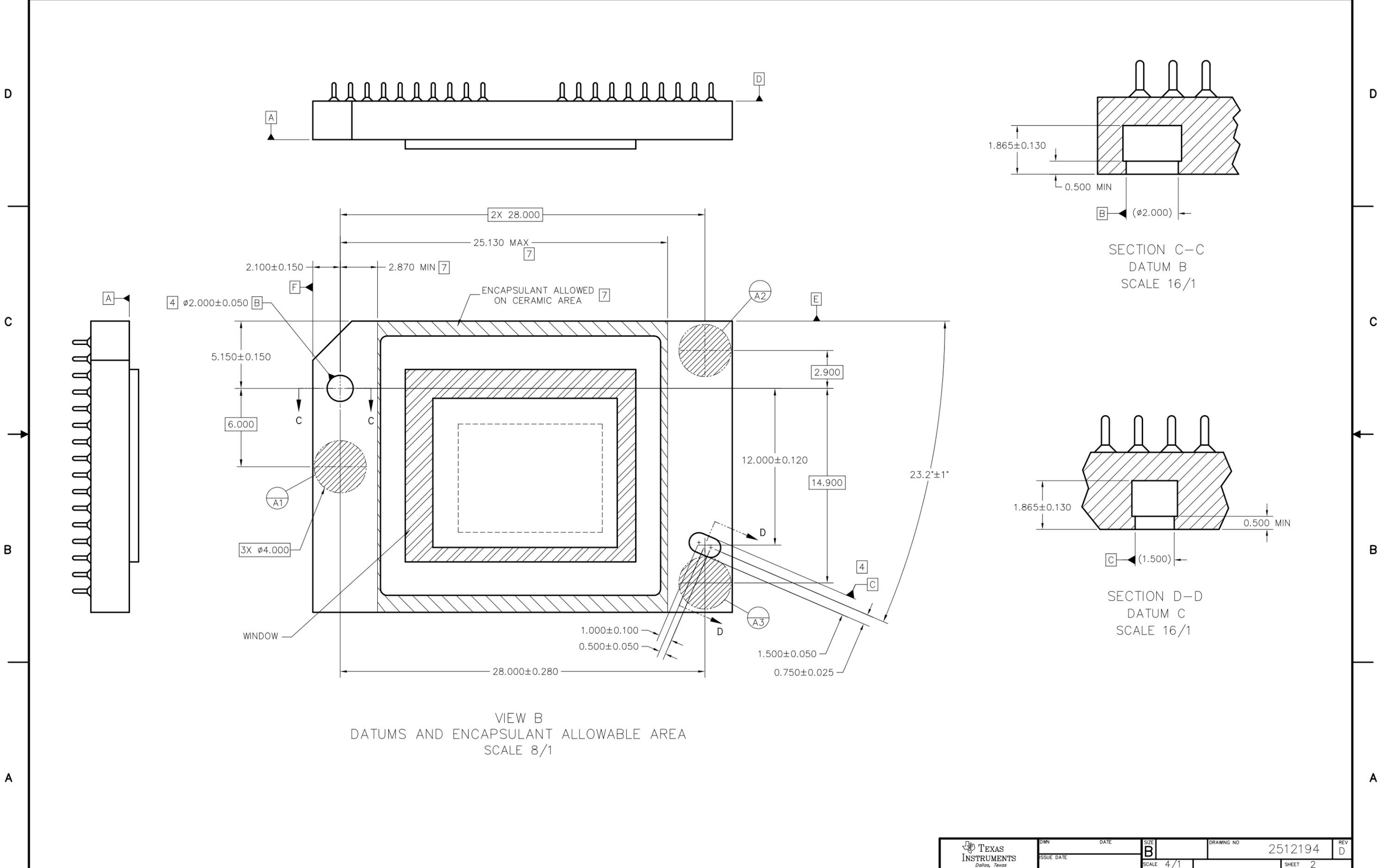


SECTION A-A
SCALE 20/1

| QTY | ITEM NO | PART OR IDENTIFYING NUMBER | NOMENCLATURE OR DESCRIPTION | NOTES |
|-----|---------|----------------------------|-----------------------------|-------|
| -1 | | | | |

| PARTS LIST | | DATE | APPROVED |
|------------|--------------|----------|----------|
| ENGR | F. ARMSTRONG | 01/17/12 | |
| QA | P. KONRAD | 01/19/12 | |
| COE | M. DORAK | 01/19/12 | |

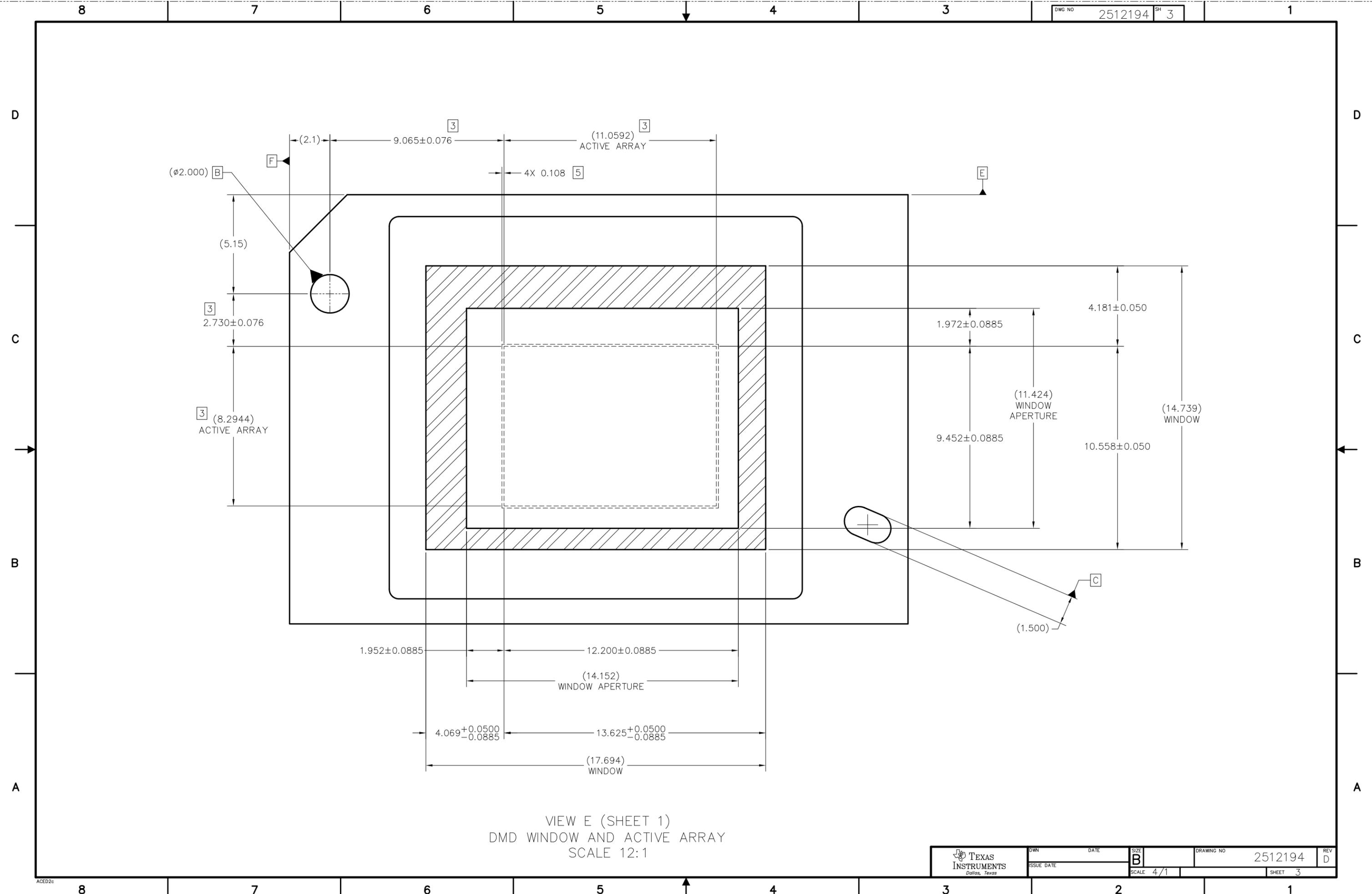
| | | | |
|--|---------|--|--------------------|
| UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS TOLERANCES: ANGLES ± 1° 2 PLACE DECIMALS ±0.25 3 PLACE DECIMALS ±0.50 | | TEXAS INSTRUMENTS Dallas, Texas | |
| REMOVE ALL BURRS AND SHARP EDGES INTERPRET DIMENSIONS IN ACCORDANCE WITH ASME Y14.5-1994 DIMENSIONAL LIMITS APPLY BEFORE PROCESSES PARENTHEITICAL INFO FOR REF ONLY | | ICD, MECHANICAL, DMD .55" XGA 2xLVDS V2 SERIES 450 (FYA PACKAGE) | |
| THIRD ANGLE PROJECTION | NONE | 0314DA | SCALE 4/1 |
| NEXT ASSY | USED ON | APPLICATION | DRAWING NO 2512194 |
| | | | REV D |
| | | | SHEET 1 OF 4 |



VIEW B
DATUMS AND ENCAPSULANT ALLOWABLE AREA
SCALE 8/1

SECTION C-C
DATUM B
SCALE 16/1

SECTION D-D
DATUM C
SCALE 16/1



(2.1)

9.065±0.076

(11.0592) ACTIVE ARRAY

(11.424) WINDOW APERTURE

4X 0.108

(∅2.000)

(5.15)

2.730±0.076

(8.2944) ACTIVE ARRAY

1.972±0.0885

4.181±0.050

9.452±0.0885

10.558±0.050

(14.739) WINDOW

1.952±0.0885

12.200±0.0885

(14.152) WINDOW APERTURE

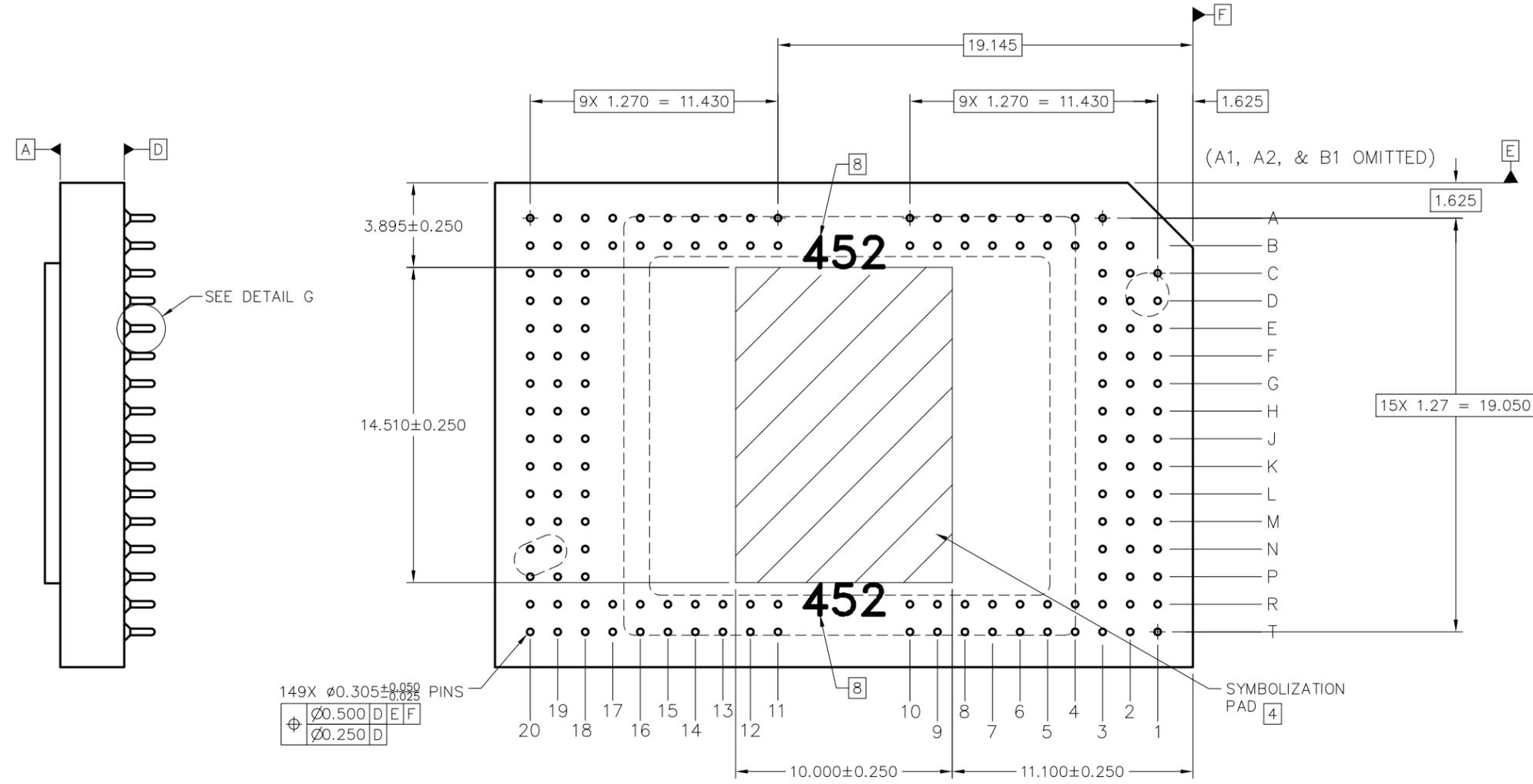
4.069^{+0.0500}_{-0.0885}

13.625^{+0.0500}_{-0.0885}

(17.694) WINDOW

(1.500)

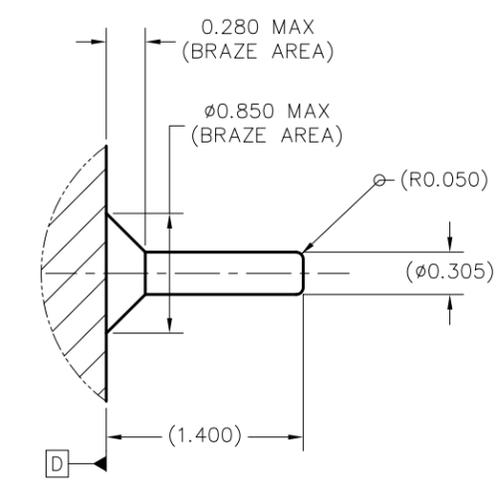
VIEW E (SHEET 1)
DMD WINDOW AND ACTIVE ARRAY
SCALE 12:1



149X $\phi 0.305 \pm 0.025$ PINS

| | | | |
|--------------|---|---|---|
| $\phi 0.500$ | D | E | F |
| $\phi 0.250$ | D | | |

VIEW F-F (SHEET 1)
PINS AND SYMBOLIZATION PAD
SCALE 8/1



DETAIL G (149 PLACES)
PIN & BRAZE DIMENSIONS
SCALE 40/1

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